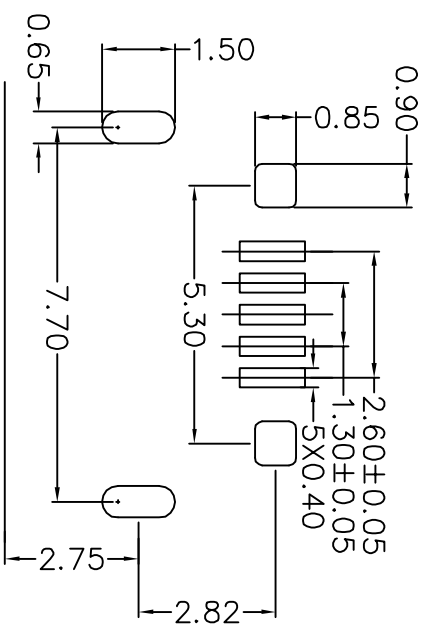


- Note:
1. Material:
 - 1.1 Housing: High temperature thermoplastic with gf,UL94V-0
 - 1.2 Contact: copper alloy,t=0.15mm
 - 1.3 Shell: copper alloy&SUS
 2. Specification:
 - 2.1 Current rating: 1 A Max.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 mΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min,0.81~2.05 Kgf Min,after 10000 insertion/extraction cycles
 - 2.7 Temperature range: -30C~80°C



PCB LAYOUT

| | | | | | |
|-------------------|-----------|------------------------|--|------------------------------------|--|
| UNITS: mm | | CSCONN | | CSCONN PRECISE ELECTRONICS CO.,LTD | |
| GENERAL TOLERANCE | | | | | |
| X. ° ±5° | 0.X ±0.25 | PART NO.(INTENDED USE) | | TITLE: MICRO USB 5P 1.2DIP 反向 | |
| X.1 ±2° | 0.XX ±0.1 | APPD: | | DWG NO. MICRO USB | |
| XX ±1° | | CHKD: Skila | | SCALE SHEET REV | |
| | | DR: Kitty | | | |

